800 W. 6th Street, Austin, TX 78701

PCN-2014-542

Assembly Site Transfer from StatsChipPac Kuala Lumpur, Malaysia (SCM) to ANST Wuxi CHINA for the CS8421-CNZ(R) component

Process/Product Change Notification

(Reference Advance PCN-2014-519)

Date: June 2014

Dear Customer:

This is a Final Announcement of the Assembly Site Transfer from StatsChipPac Kuala Lumpur, Malaysia (SCM) to ANST Wuxi CHINA for the CS8421–CNZ(R) component that is currently offered by Cirrus Logic. This Final announcement is a follow on to the Advance PCN notification communicated to all customers in February of this calendar year 2014. The details of this Assembly Site Transfer are outlined on the following pages.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the lifetime buy offering/discontinuance plan.

The described change(s) within this PCN will not be realized or take effect any earlier than **60** days from the date of this notification, unless a customer agreement has been reached on an earlier implementation of the change or successful completion of the defined qualification has been realized.

Please note that the notification period has been reduced from 90 days to 60 days as the SCM site recently informed Cirrus that the closure date has been moved forward from December 31st, 2014 to September 30th, 2014. Cirrus has no control over any changes to the site closure date.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Cirrus Logic would like to take this opportunity to thank our customers for their cooperation and assistance in this respective matter. Any specific or immediate inquiries should be directed to your local Field Sales Representative.

Sincerely,

Cirrus Logic Corporate Quality
Phone: +1(512) 851-4000

Attachment: 1

Products Affected:

The devices listed on this page are the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

Technical details of this Process / Product Change follow on the next page(s).

PCN Number:	2014-542		**PCN Date:**	June 2014	
Title:	Assembly Site Transfer from StatsChipPac Kuala Lumpur, Malaysia to ANST Wuxi CHINA for the CS8421-CNZ(R) component				
Customer Contact:	Local Field Sales Representative	**Phone:**	**(512) 851-4000**	**Dept:**	**Corporate Quality**
Proposed 1st Ship Date:	August 2014	**Estimated Sample Availability date:**	June 2014		
Change Type:	Assembly Site Transfer to an existing Qualified Cirrus Logic Site Location: Change Type = Major				

☒	**Assembly Site**	☐	**Assembly Process**	☒	**Assembly Materials**
☐	**Design**	☐	**Electrical Specification**	☐	**Mechanical Specification**
☐	**Test Site**	☐	**Packing/Shipping/Labeling**	☐	**Test Process**
☐	**Wafer Bump Site**	☐	**Wafer Bump Material**	☐	**Wafer Bump Process**
☐	**Wafer Fab Site**	☐	**Wafer Fab Materials**	☐	**Wafer Fab Process**

PCN Details

Description of Change:

Cirrus Logic's package Assembly and Test Supplier, StatsChipPac, has announced their site in Kuala Lumpur, Malaysia will close by September 30th, 2014.

Cirrus Logic is qualifying and will move these products to the existing qualified subcontractor (ANST) site location in Wuxi CHINA.

Below you will find an outline of the described changes for these components:

CS8421-CNZ(R)

- **Assembly Site Change:**
  From: **StatsChipPac Kuala Lumpur, Malaysia** → To: **ANST Wuxi CHINA**
- **PackMark COO Symbolization:**
  From: **MYS** → To: **CHN**
- **Mold Compound:**
  From: **Sumitomo EME-G770** → To: **Hitachi CEL-9240HF**

Reason for Change:

Cirrus Logic's package Assembly and Test Supplier, StatsChipPac, has announced their site in Kuala Lumpur, Malaysia will close by September 30th, 2014.

Cirrus Logic is qualifying and will move these products to the existing qualified subcontractor (ANST) site location in Wuxi CHINA.

Special Note:

As a full services supplier and in order to ensure continuity of supply as well as sustain quality an accelerated timeframe has been established for the full transfer of said product no later than September 30th, 2014.

Earlier production level material may be available from the qualified subcontractor (ANST) site location in Wuxi CHINA, but shipment(s) from Cirrus Logic are contingent on successful completion of the designated site transfer qualification.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

Anticipated No Adverse Impact to the Quality & Reliability of said product; as Transfer Site is an existing Cirrus Logic qualified subcontractor (ANST) site (Wuxi CHINA) and considered low risk.

Product Affected:	☒ **Table I**

	Customer Material Part Number	**Cirrus Logic Part Number**
Device 1:		CS8421-CNZ(R)

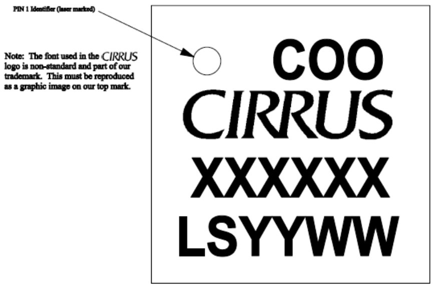
Changes to product identification resulting from this PCN:

The Cirrus Logic component symbolization on the external face of the device reflects the designated Country Of Origin.

Below you will find a representative example:

Our part: **CS8421-CNZ (R)**
Mark format: **234**
Mark change:
· Assembly vendor = None (not shown on mark)
· COO = changing From: **MYS** → TO: **CHN**

Line 1: Country Of Origin (COO)
Line 2: Logo Line
Line 3: Part Number (6 spaces max.)
Line 4: Package Mark (6 spaces max.)



Note: The font used in the CIRRUS logo is non-standard and part of our trademark. This must be reproduced as a graphic image on our top mark.

With the Assembly Site Transfer to ANST Wuxi CHINA, the material will receive the appropriate designation for the Country Of Origin.

Qualification Data:

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
Qualification Schedule:	**Start:**	March 2014	**End:**	July 2014

Qualification Device Construction Details:

	Device 1	**Device 2**
Part Number(s):	CS8421-CNZ(R)	
Wafer Fab Site:	YF	
Wafer Technology:	0.25	
Die Size:	7.025 mm	
Assembly Site:	ANST Wuxi CHINA	
Package Type/Code:	20QFN5Z 5x5	
Moisture Level:	MSL (Moisture Sensitivity Level) 3	
Package Pins:	20 NL QFN	
Lead Frame Material:	Cu (Copper)	
Mold Compound Supplier:	CEL–9240HF Hitachi	
Lead Finish:	Matte Sn Plate	
Die Attach Material	Ablebond 8290	
Wire Diameter:	0.8mil	
Wire Base Metal:	Au (Gold)	

The Qualification Plans are designed using JEDEC and other applicable industry standards. An overall summary of the Qualification results will be submitted upon completion.

CS8421-CNZ(R) Qualification

CS8421-CNZ(R) Qualification: ☒ **Plan** ☐ **Test Results**

Reliability Test			Sample Size (PASS/FAIL)
Pre-Conditioning	JEDEC J-STD-020A	MSL3 / 260°C (1 Lot)	231 / 0
THB (Temperature Humidity Bias)	JESD22 A101	85C/85%RH/1000 Hrs (THB) (1 Lot)	77 / 0
TC (Temperature Cycle)	JESD22 A104	-65°C to +150°C for 500 cycles (1 Lots)	77 / 0
WBS (Wire Bond Shear)	JESD22 B116	Paragraph 4 (Procedure) (1 Lot)	5 units / lot
WBP (Wire Bond Pull)	MIL-STD-883 Method 2011	Paragraph 3 (Procedure) (1 Lot)	5 units / lot
SD (Solderability)	JESD22 B102	93°C / 8 Hr steam age before SD (1 Lot)	15 units / lot
PD (Physical Dimensions)	JESD22 B100 + B108	Package outline per JESD95 Cpk > 1.50 per JESD95 (1 Lot)	20 / 0
HTSL (High Temperature Storage Life)	JESD22 A103	150°C for 1000 Hrs (1 Lot)	45 / 0

Notes:

- Qualification tests “pass” on zero fails for each test